Low Plastic Quad Flatpack Package with Top Exposed Pad (LQFP-TEP)





Q128.14x20B

128 Lead Low Quad Flatpack with Top Exposed Pad

_	MILLIMETERS BHB			_
А	-	-	1.60	
A1	0.05	-	0.15	13
A2	1.35	1.40	1.45	
D		22 BSC		4
D1		20 BSC		7, 8
D2		12.20 BSC		14
Е		16 BSC		4
E1		14 BSC		7, 8
E2		8.35 BSC		14
L	0.45	0.60	0.75	
Ν		128		
е		0.50 BSC		
b	0.17	0.22	0.27	9
b1	0.17	0.20	0.23	
CCC			0.08	
ddd			0.08	

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- 1. Dimensioning and tolerancing conform to AMSE Y14.5m-1994.
- 2. Datum plane H located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- 3. Datums A-B and D to be determined at center lines between leads where leads exit plastic body at datum plane H.
- 4. To be determined at seating plane C.

NOTES:

- 5. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.254mm per side on D1 and E1 dimensions.
- 6. "N" is the total number of terminals.
- 7. These dimensions to be determined at datum plane H.
- Package top dimensions are smaller than package bottom dimensions and top of package will not overhang bottom of package.
- Dimension b does not include dambar protrusion. Allowable dambar protrusion shall not be 0.08mm total in excess of the b dimension at maximum material condition. Dambar cannot be located at the lower radius or the foot.
- 10. Controlling dimension: millimeter.
- 11. Maximum allowable die thickness to be assembled in this package family is 0.38 millimeters.
- 12. This outline conforms to JEDEC publication 95 Registration MS-026, variations BHA & BHB.
- 13. A1 is defined as the distance from the seating plane to the lowest point of the package body.
- Dimensions D2 and E2 represent the size of the exposed pad. The actual dimensions may be reduced up to 0.76mm due to mold flash.

